

2SB1156

Silicon PNP epitaxial planar type

For power switching

Complementary to 2SD1707

■ Features

- Low collector-emitter saturation voltage $V_{CE(sat)}$
- Satisfactory linearity of forward current transfer ratio h_{FE}
- Large collector current I_C
- Full-pack package which can be installed to the heat sink with one screw

■ Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	-130	V
Collector-emitter voltage (Base open)	V_{CEO}	-80	V
Emitter-base voltage (Collector open)	V_{EBO}	-7	V
Collector current	I_C	-20	A
Peak collector current	I_{CP}	-30	A
Collector power dissipation	P_C	100	W
	$T_a = 25^\circ\text{C}$	3	
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

■ Electrical Characteristics $T_C = 25^\circ\text{C} \pm 3^\circ\text{C}$

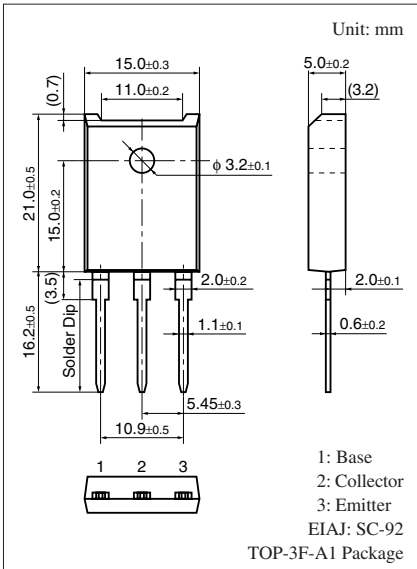
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -10 \text{ mA}, I_B = 0$	-80			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -100 \text{ V}, I_E = 0$			-10	μA
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = -5 \text{ V}, I_C = 0$			-50	μA
Forward current transfer ratio	h_{FE1}	$V_{CE} = -2 \text{ V}, I_C = -0.1 \text{ A}$	45			—
	h_{FE2}^*	$V_{CE} = -2 \text{ V}, I_C = -3 \text{ A}$	60		260	
	h_{FE3}	$V_{CE} = -2 \text{ V}, I_C = -10 \text{ A}$	30			
Collector-emitter saturation voltage	$V_{CE(sat)1}$	$I_C = -8 \text{ A}, I_B = -0.4 \text{ A}$			-0.5	V
	$V_{CE(sat)2}$	$I_C = -20 \text{ A}, I_B = -2 \text{ A}$			-1.5	
Base-emitter saturation voltage	$V_{BE(sat)1}$	$I_C = -8 \text{ A}, I_B = -0.4 \text{ A}$			-1.5	V
	$V_{BE(sat)2}$	$I_C = -20 \text{ A}, I_B = -2 \text{ A}$			-2.5	
Transition frequency	f_T	$V_{CE} = -10 \text{ V}, I_C = -0.5 \text{ A}, f = 10 \text{ MHz}$		30		MHz
Turn-on time	t_{on}	$I_C = -8 \text{ A}, I_{B1} = -0.8 \text{ A}, I_{B2} = 0.8 \text{ A}$		0.5		μs
Storage time	t_{stg}	$V_{CC} = -50 \text{ V}$		1.0		μs
Fall time	t_f			0.2		μs

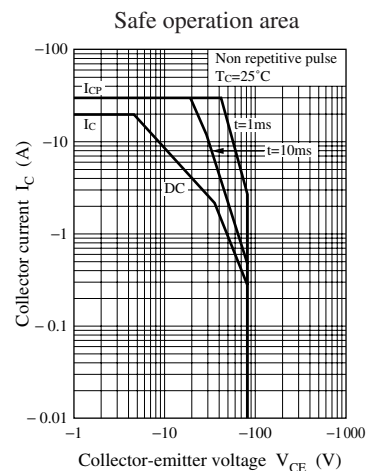
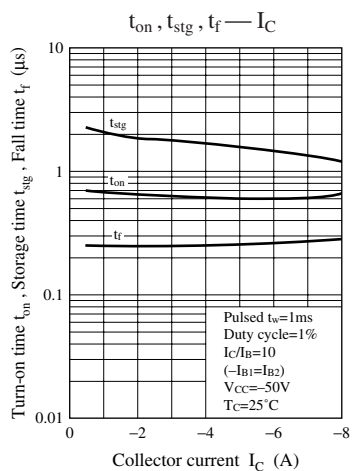
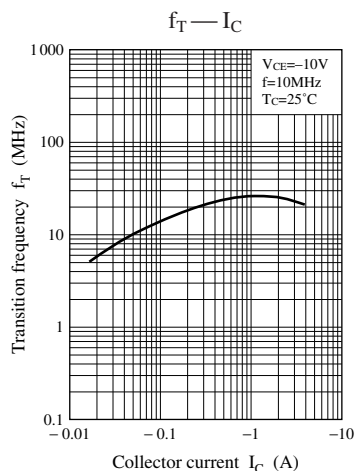
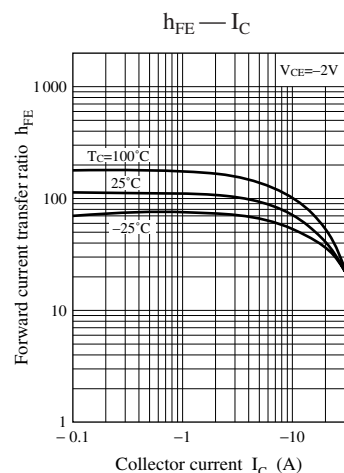
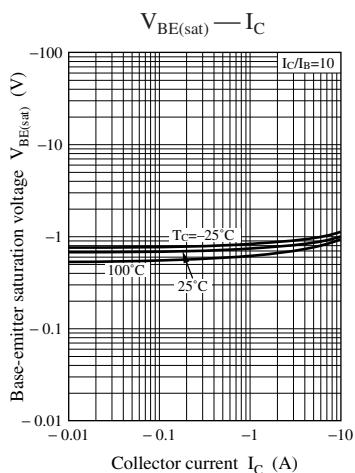
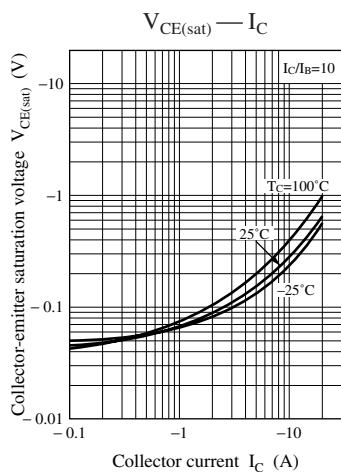
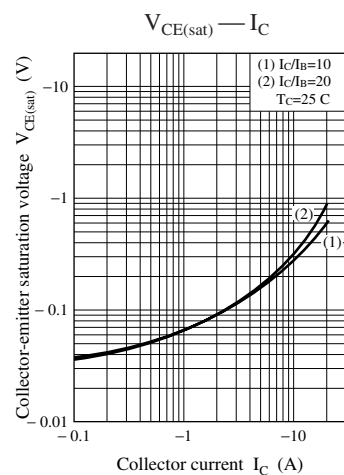
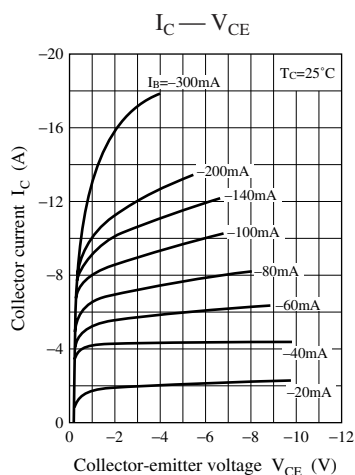
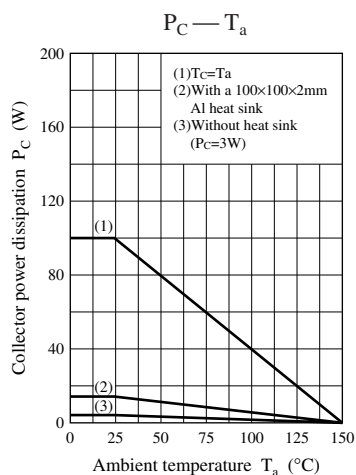
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

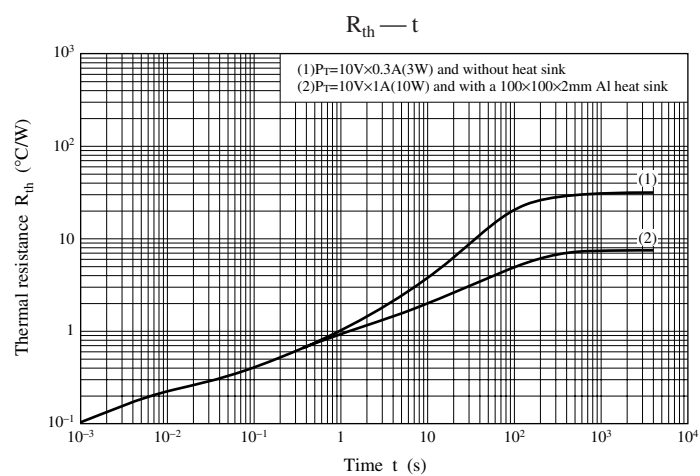
2. *: Rank classification

Rank	R	Q	P
h_{FE2}	60 to 120	90 to 180	130 to 260

Ordering can be made by the common rank (PQ rank $h_{FE2} = 60$ to 240) in the rank classification.







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